



Call for Papers

Abstract Due June 21, 2024

**2024 8th International Workshop on Low Temperature Bonding
for 3D Integration
(LTB-3D 2024, WaferBond 2024 East)**

Oct. 30-Nov. 1, 2024, Nara-city, Japan

Sponsored by

General Incorporated Non-profit Association - Institute for Advanced Micro-System Integration (IMSI)

Technically Co-sponsored by

The Electrochemical Society (to be confirmed)

IEEE Electronics Packaging Society Japan Chapter (to be confirmed)

Endorsed by

The Japan Society of Applied Physics (JSAP) (to be confirmed)



2024 8th International Workshop on Low Temperature Bonding for 3D Integration

2024 8th International Workshop on Low Temperature Bonding for 3D Integration (LTB-3D 2024) will be held in Oct. 30-Nov. 1, 2024, in Nara-city, Japan.

The LTB-3D is a premier conference series sponsored by General Incorporated Non-profit Association - Institute for Advanced Micro-System Integration (IMSI), technically co-sponsored by The Electrochemical Society and The IEEE EPS Japan Chapter. Preceding LTB-3D workshop was held in Tokyo, Japan in its 1st (2007), 2nd (2010), 3rd (2012), 4th (2014), and 5th (2017) versions and in Kanazawa in 6th (2019) version. Its 7th version, LTB-3D 2021, was held online. LTB-3D 2024 is given in Nara, an ancient capital of Japan as WaferBond 2024 EAST in conjunction with WaferBond conferences which are held in Europe: 2009 (Grenoble), 2011 (Chemnitz), 2013 (Stockholm), 2015 (Braunschweig), 2017 (Leuven), 2019 (Halle/Saale), and 2021 (Schmalkalden).

This workshop is focusing on the promotion of advanced research areas related to low-temperature bonding technologies, including surface activated bonding (SAB) and atomic diffusion bonding (ADB), which realize novel device structure by heterogeneous material and device integration and lead to entirely new manufacturing approaches to 3D and module integration of semiconductor devices, photonics systems, and power electronic systems. These bonding technologies have been already used for the volume production and have potential applications in wide range of manufacturing industries. This workshop will be held as a single-track seminar to provide a compact forum for close and deep discussion of all aspects of low temperature bonding technologies — the latest technologies and applications, as well as business opportunities.

● Scope

- Roles of Low-temperature Bonding in 3D and Hetero-Integration
- Surface Activated Bonding (SAB) and its Extensions
- Hydrophilic and Plasma-assisted Bonding
- Metal and Hybrid Bonding
- New process for Low-temperature Bonding
- Power, RF, Photonic, and MEMS device Applications
- New Applications of Low-temperature Bonding
- Fundamentals and characterization
- Equipment and Quality Assessments

● Important Date

Abstract submission deadline ————— **June 21, 2024**
Acceptance/Rejection notification ————— **July 26, 2024**
Final manuscript and presentation material deadline ————— **Aug. 30, 2024**
Conference ————— **Oct. 30–Nov. 1, 2024**

● JJAP Special Issue

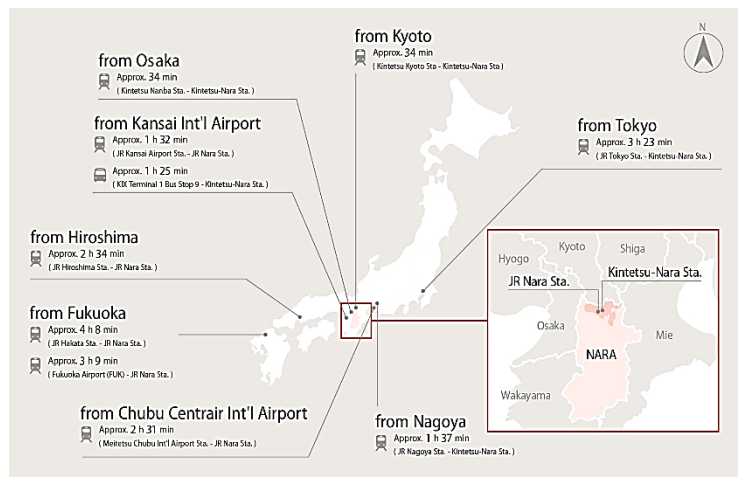
Special Issue of Japanese Journal of Applied Physics will be published as journal related to LTB-3D 2024.

● Venue

Nara Kasugano International Forum “IRAKA”



● Access to Nara



● For further information, get in touch with <https://imsi.jp/ltb3d/ltb3d-2024/index.html> (under preparation)

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